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AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claim 1 (currently amended): A method of wiring formation comprising the steps of:

- forming a feeder film partially on a substrate;
- forming on the substrate a plating base film such that the plating base film partially overlaps the feeder film;
- forming a plated wiring on the plating base film; and
- selectively removing at least a portion of the feeder film that is exposed from the plated wiring such that the feeder film under the plating base film remains.

Claim 2 (original): A method of wiring formation according to Claim 1, wherein the step of forming on the substrate a plating base film is performed using a physical film making process.

Claim 3 (original): A method of wiring formation according to Claim 1, wherein the step of forming a plated wiring on the plating base film is performed using an electrolytic plating process.

Claim 4 (original): A method of wiring formation according to Claim 1, wherein the step of selectively removing at least a portion of the feeder film that is exposed from the plated wiring is performed using a wet etching process.

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Claim 5 (original): A method of wiring formation according to Claim 1, wherein a width of a portion of the plating base film that is stacked on the feeder film is wider than the smallest wire width of the feeder film.

Claim 6 (original): A method of wiring formation according to Claim 1, wherein the plating base film comprises at least one of an adhesive layer and a diffusion preventive layer.

Claim 7 (currently amended): A method of wiring formation comprising the steps of:

forming a feeder film partially on a substrate;

forming on the substrate a resist pattern which has an opening defining a wiring forming area, such that a portion of the feeder film is exposed from the opening in the resist pattern;

forming a plating base film at least on the substrate in the opening such that the plating base film partially overlaps the portion of the feeder film exposed from the opening;

forming a plated wiring on the plating base film in the opening;

removing the resist pattern; and

selectively removing at least a portion of the feeder film that is exposed from the plated wiring such that the feeder film under the plating base film remains.

Claim 8 (original): A method of wiring formation according to Claim 7, wherein the step of forming on the substrate a plating base film is performed using a physical film making process.

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Claim 9 (original): A method of wiring formation according to Claim 7, wherein the step of forming a plated wiring on the plating base film is performed using an electrolytic plating process.

Claim 10 (original): A method of wiring formation according to Claim 7, wherein the step of selectively removing at least a portion of the feeder film that is exposed from the plated wiring is performed using a wet etching process.

Claim 11 (original): A method of wiring formation according to Claim 7, wherein a width of a portion of the plating base film that is stacked on the feeder film is wider than the smallest wire width of the feeder film.

Claim 12 (original): A method of wiring formation according to Claim 7, wherein the plating base film comprises at least one of an adhesive layer and a diffusion preventive layer.

Claim 13 (currently amended): A method of manufacturing an electronic component comprising the steps of:

- providing a substrate;
- forming a feeder film partially on the substrate;
- forming on the substrate a plating base film by using a physical film making process such that the plating base film partially overlaps the feeder film;
- forming a plated wiring on the plating base film using an electrolytic plating process; and
- selectively removing at least a portion of the feeder film that is exposed from the plated wiring such that the feeder film under the plating base film remains, using a wet etching process; wherein
- the plating base film includes a diffusion preventive layer.

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Claim 14 (original): A method according to Claim 13, wherein a width of a portion of the plating base film that is stacked on the feeder film is wider than the smallest wire width of the feeder film.

Claim 15 (previously presented): A method according to Claim 16, wherein a width of a portion of the plating base film that is stacked on the feeder film is wider than the smallest wire width of the feeder film.

Claim 16 (original): A method according to Claim 13, wherein the plating base film comprises at least one of an adhesive layer and a diffusion preventive layer.

Claim 17 (currently amended): A method of manufacturing an electronic component comprising the steps of:

providing a substrate;

forming a feeder film partially on a substrate;

forming on the substrate a resist pattern which has an opening defining a wiring forming area, such that a portion of the feeder film is exposed from the opening in the resist pattern;

forming a plating base film at least on the substrate in the opening such that the plating base film partially overlaps the portion of the feeder film exposed from the opening using a physical film making process;

forming a plated wiring on the plating base film in the opening using an electrolytic plating process;

removing the resist pattern; and

selectively removing at least a portion of the feeder film that is exposed from the plated wiring, using a wet etching such that the feeder film under the plating base film remains; wherein

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the plating base film includes a diffusion preventive layer.

Claim 18 (original): A method according to Claim 17, wherein a width of a portion of the plating base film that is stacked on the feeder film is wider than the smallest wire width of the feeder film.

Claim 19 (previously presented): A method according to Claim 20, wherein a width of a portion of the plating base film that is stacked on the feeder film is wider than the smallest wire width of the feeder film.

Claim 20 (original): A method according to Claim 17, wherein the plating base film comprises at least one of an adhesive layer and a diffusion preventive layer.

Claim 21-24 (canceled).

Claim 25 (previously presented): A method according to Claim 1, further comprising a step of forming on the substrate a resist pattern having a reversed [taped] shape.

Claim 26 (previously presented): A method according to Claim 1, wherein the plating base film comprises an adhesive layer.

Claim 27 (new): A method of wiring formation comprising the steps of:
forming a feeder film partially on a substrate;
forming on the substrate a plating base film such that the plating base film partially overlaps the feeder film;
forming a plated wiring on the plating base film; and
selectively removing at least a portion of the feeder film that is exposed from the

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plated wiring such that the feeder film under the plating base film is completely removed.

Claim 28 (new): A method of wiring formation according to Claim 27, wherein the step of forming on the substrate a plating base film is performed using a physical film making process.

Claim 29 (new): A method of wiring formation according to Claim 27, wherein the step of forming a plated wiring on the plating base film is performed using an electrolytic plating process.

Claim 30 (new): A method of wiring formation according to Claim 27, wherein the step of selectively removing at least a portion of the feeder film that is exposed from the plated wiring is performed using a wet etching process.

Claim 31 (new): A method of wiring formation according to Claim 27, wherein a width of a portion of the plating base film that is stacked on the feeder film is wider than the smallest wire width of the feeder film.

Claim 32 (new): A method of wiring formation according to Claim 27, wherein the plating base film comprises at least one of an adhesive layer and a diffusion preventive layer.